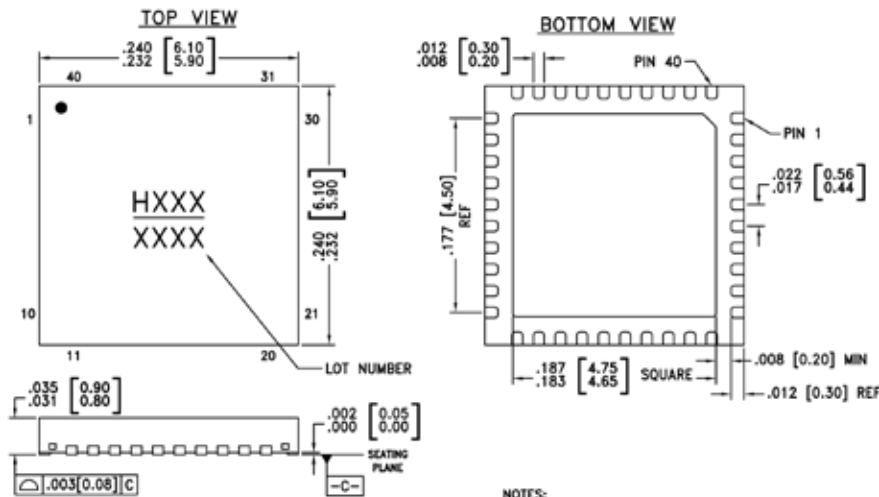
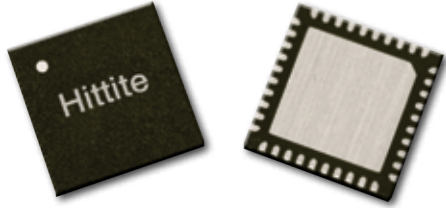


6 X 6 MM QUAD FLATPACK NO-LEAD (QFN) PLASTIC PACKAGE

LP6G(E) Package Outline Drawing


NOTES:

1. PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
2. LEAD AND GROUND PADDLE MATERIAL: COPPER ALLOY.
3. LEAD AND GROUND PADDLE PLATING: 100% MATTE TIN.
4. DIMENSIONS ARE IN INCHES [MILLIMETERS].
5. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
6. CHARACTERS TO BE HELVETICA MEDIUM, .025 HIGH, WHITE INK, OR LASER MARK LOCATED APPROX. AS SHOWN.
7. PAD BURR LENGTH SHALL BE 0.15mm MAX. PAD BURR HEIGHT SHALL BE 0.25mm MAX.
8. PACKAGE WARP SHALL NOT EXCEED 0.05mm
9. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
10. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED PCB LAND PATTERN.

Package Information

Part Number Suffix	Package Body Material	Lead Finish	MSL Rating	Package Marking ^{[3][4]}
LP6G	RoHS Compliant Mold Compound	Sn/Pb Solder	MSL1 ^[1]	HNNN XXXX
LP6GE	RoHS Compliant Mold Compound	100% matte Sn	MSL1 ^[2]	HNNN XXXX

[1] Max peak reflow temperature of 235 C

[2] Max peak reflow temperature of 260 C

[3] 4-Digital lot number XXXX

[4] 3-Digit part number NNN



**6 X 6 MM QUAD FLATPACK
 NO-LEAD (QFN) PLASTIC PACKAGE**

Suggested LP6G(E) PCB Land Pattern

